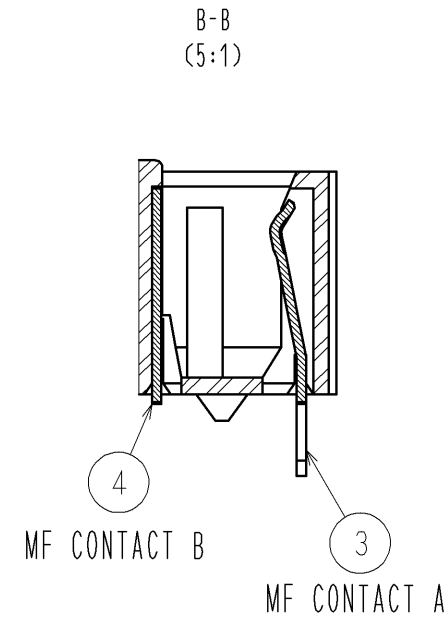
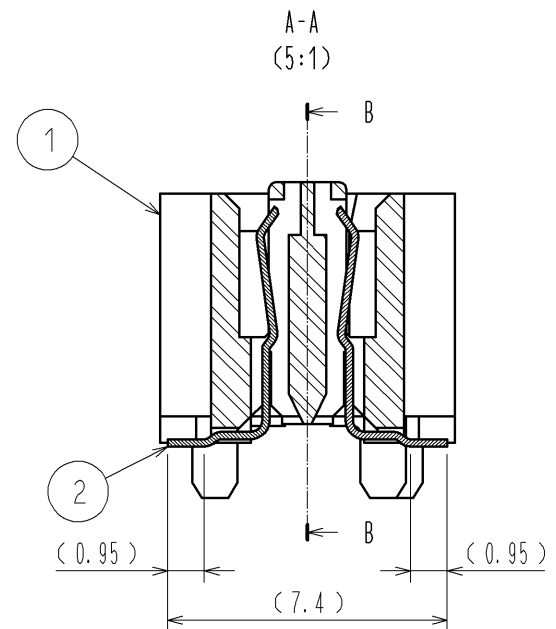
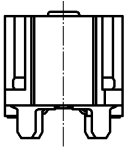
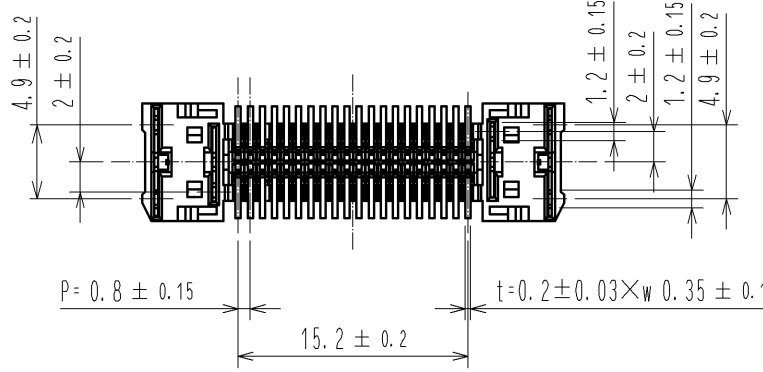
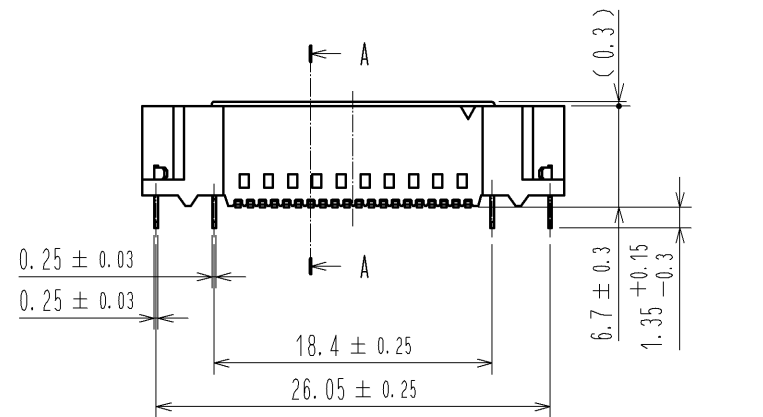
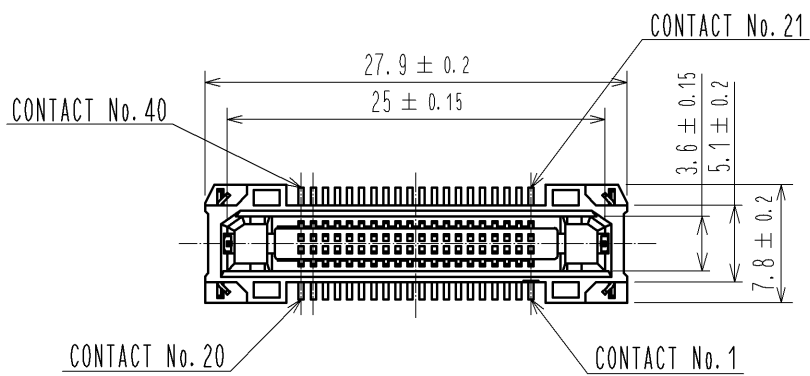
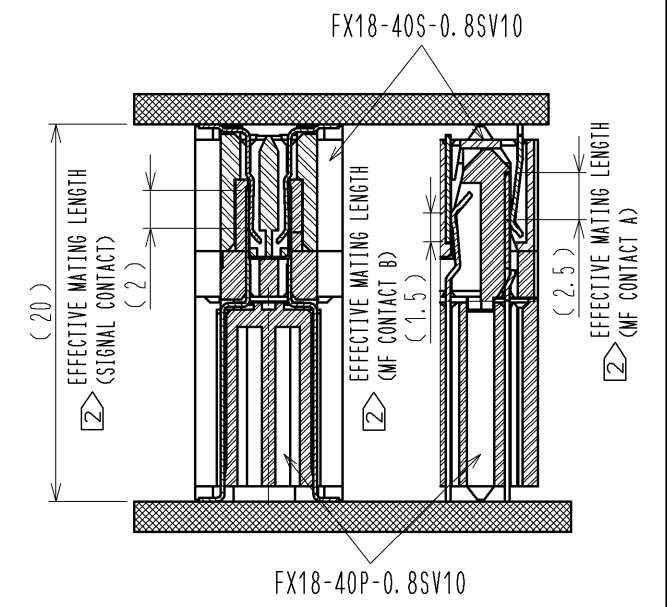
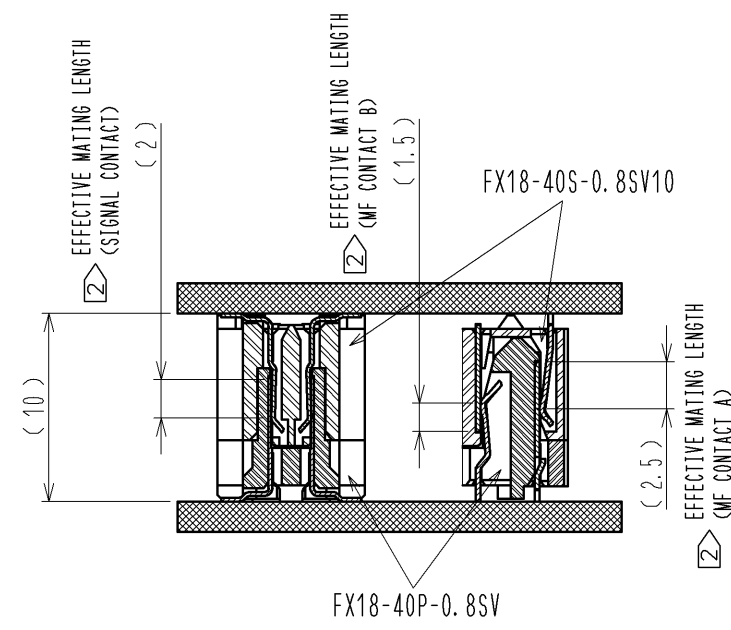


APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾ 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 30 N MAX. WITHDRAWAL FORCE: 3 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT. APPLY 0.4A WHEN ALL THE CONTACTS ARE USED FOR CURRENT CARRYING. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	14. 07. 16
			CHECKED	HT. YAMAGUCHI	14. 07. 15
			DESIGNED	TH. SANO	14. 07. 15
			DRAWN	TH. SANO	14. 07. 15
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-349387-00
HRS	SPECIFICATION SHEET		PART NO.	FX18-40S-0.8SV10	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0055-1-00	△ 1/1

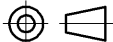





CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=10mm

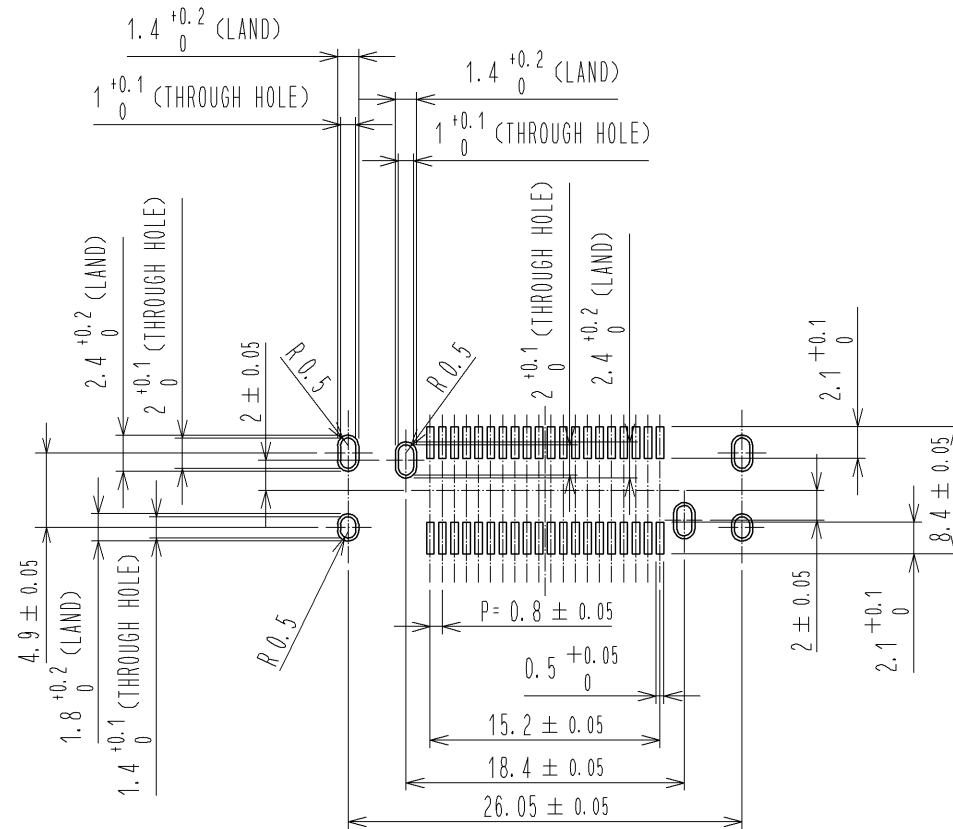
CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=20mm



- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- 5 THIS IS PACKAGED IN TRAY. (70pcs/TRAY)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

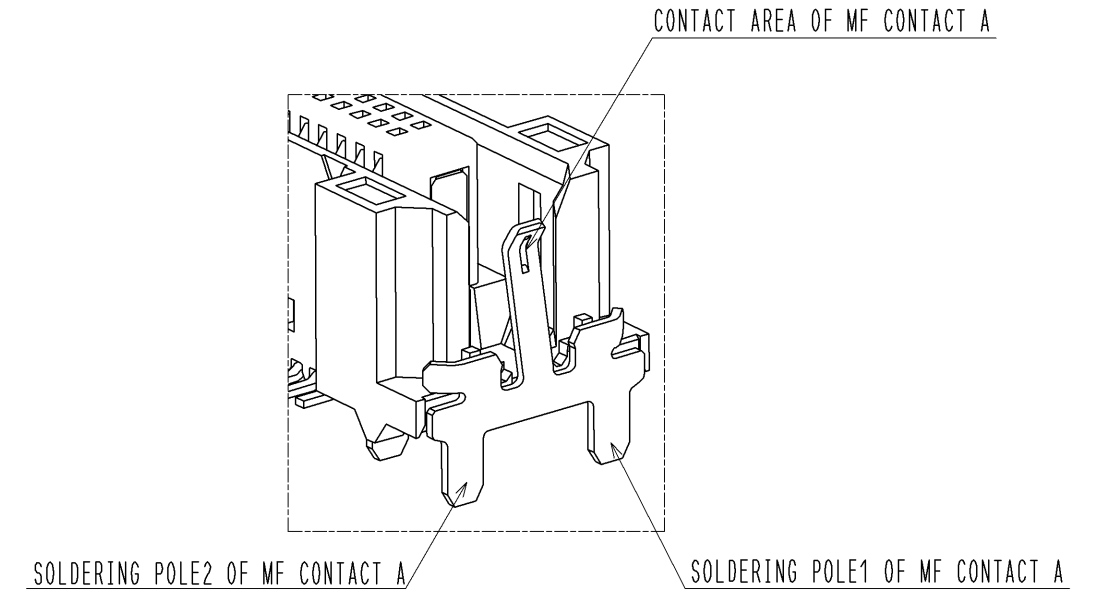
			6	POLYIMIDE													
			5	POLYSTYRENE													
			4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm												
					LEAD AREA:TIN-PLATING 1 μm												
					UNDER PLATING:NICKEL 1.3 μm												
2	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm			3	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm										
		LEAD AREA:GOLD 0.03 μm					LEAD AREA:TIN-PLATING 1 μm										
		UNDER PLATING:NICKEL 1.3 μm					UNDER PLATING:NICKEL 1.3 μm										
1	POLYAMIDE	BLACK UL94V-0															
NO.		MATERIAL			FINISH , REMARKS		NO.		MATERIAL		FINISH , REMARKS						
UNITS mm				SCALE 2 : 1				COUNT		DESCRIPTION OF REVISIONS		DESIGNED		CHECKED		DATE	
 HIROSE ELECTRIC CO., LTD.				APPROVED : HS. OKAWA				14. 07. 16		DRAWING NO. EDC3-349387-00							
				CHECKED : HT. YAMAGUCHI				14. 07. 15		PART NO. FX18-40S-0.8SV10							
				DESIGNED : TH. SANO				14. 07. 15		CODE NO. CL579-0055-1-00							
				DRAWN : TH. SANO				14. 07. 15									
																 1/2	

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS: $t=1.6\text{mm}$ METAL MASK THICKNESS: $t=0.12\text{mm}$)

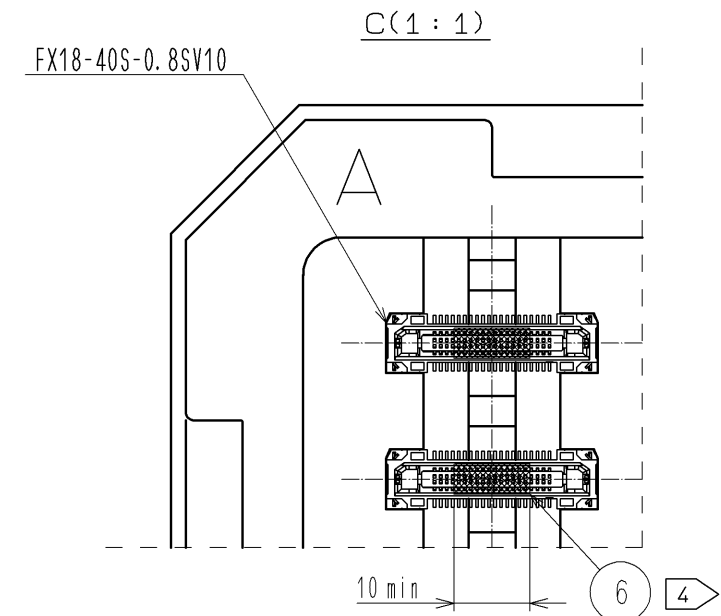
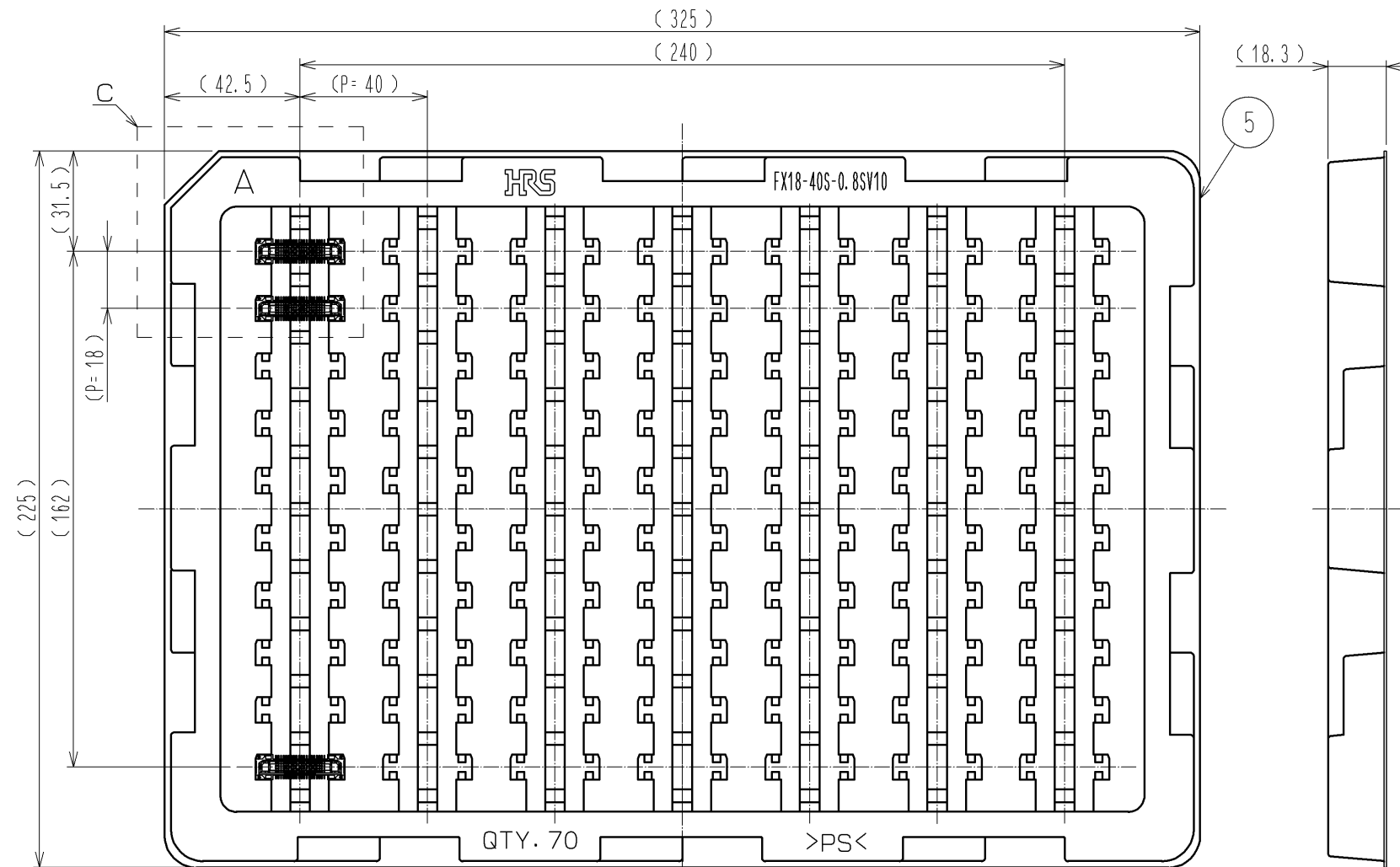


5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS

DRAWING NO.	EDC3-349387-00
PART NO.	FX18-40S-0.8SV10
CODE NO.	CL579-0055-1-00

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